

STARPOWER

SEMICONDUCTOR™

IGBT

GD600HFT60C2S

Preliminary

Molding Type Module**600V/600A 2 in one-package**

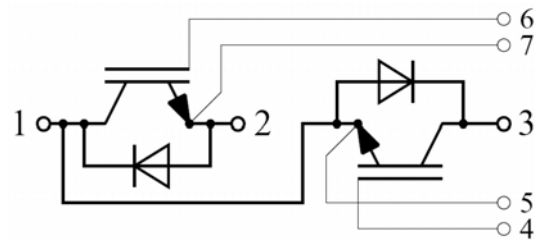
General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as UPS and SMPS.



Features

- Low $V_{CE(sat)}$ trench IGBT technology
- Low switching losses
- 5 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



Equivalent Circuit Schematic

Typical Applications

- UPS
- Switching mode power supplies
- Electronic welders

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD600HFT60C2S	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	950	A
	@ $T_C=80^\circ\text{C}$	600	
$I_{CM(1)}$	Pulsed Collector Current $t_p=1\text{ms}$	1200	A
I_F	Diode Continuous Forward Current	600	A
I_{FM}	Diode Maximum Forward Current	1200	A
P_D	Maximum Power Dissipation @ $T_J=175^\circ\text{C}$	2027	W
T_{SC}	Short Circuit Withstand Time @ $T_J=150^\circ\text{C}$	5	μs
T_J	Maximum Junction Temperature	175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}, t=1\text{min}$	2500	V
Mounting Torque	Power Terminal Screw:M6	2.5 to 5.0	N.m
	Mounting Screw:M6	3.0 to 5.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^\circ\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_J=25^\circ\text{C}$	600			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V},$ $T_J=25^\circ\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V},$ $T_J=25^\circ\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=6.0\text{mA}, V_{CE}=V_{GE},$ $T_J=25^\circ\text{C}$	4.0		6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=600\text{A}, V_{GE}=15\text{V},$ $T_J=25^\circ\text{C}$		1.60	2.05	V
		$I_C=600\text{A}, V_{GE}=15\text{V},$ $T_J=175^\circ\text{C}$		2.00		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=400V, I_C=600A,$ $R_G=0.8\Omega, V_{GE}=15V,$ $T_J=25^\circ C$		31		ns
t_r	Rise Time			66		ns
$t_{d(off)}$	Turn-Off Delay Time			170		ns
t_f	Fall Time			64		ns
E_{on}	Turn-On Switching Loss			25.3		mJ
E_{off}	Turn-Off Switching Loss			17.4		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=400V, I_C=600A,$ $R_G=0.8\Omega, V_{GE}=15V,$ $T_J=175^\circ C$		37		ns
t_r	Rise Time			70		ns
$t_{d(off)}$	Turn-Off Delay Time			210		ns
t_f	Fall Time			82		ns
E_{on}	Turn-On Switching Loss			35.4		mJ
E_{off}	Turn-Off Switching Loss			24.6		mJ
C_{ies}	Input Capacitance	$V_{CE}=30V, f=1MHz,$ $V_{GE}=0V$		46.3		nF
C_{oes}	Output Capacitance			3.18		nF
C_{res}	Reverse Transfer Capacitance			1.38		nF
I_{SC}	SC Data	$t_{SC} \leq 5\mu s, V_{GE}=15V,$ $T_J=150^\circ C, V_{CC}=360V,$ $V_{CEM} \leq 600V$		TBD		A
R_{Gint}	Internal Gate Resistance			0.8		Ω
L_{CE}	Stray Inductance				20	nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip	$T_C=25^\circ C$		0.35		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

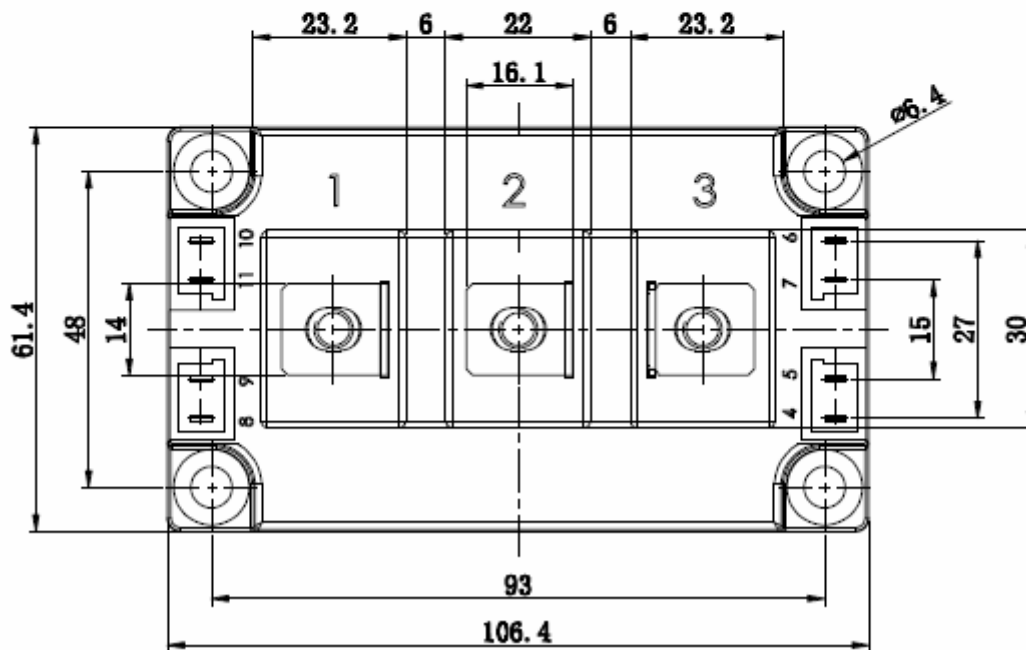
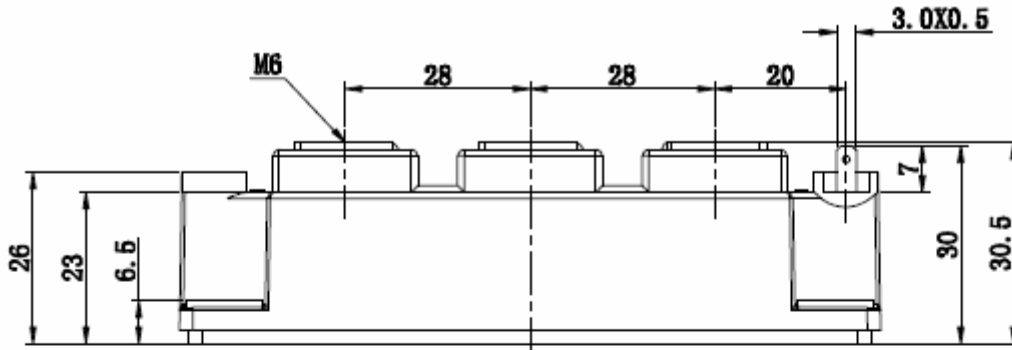
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=600A$	$T_J=25^\circ C$	1.40	1.80	V
			$T_J=125^\circ C$		1.45	
Q_r	Recovered Charge	$I_F=600A,$	$T_J=25^\circ C$	25.2		μC
			$T_J=125^\circ C$	33.0		
I_{RM}	Peak Reverse Recovery Current	$V_R=300V,$ $di/dt=-6000A/\mu s,$	$T_J=25^\circ C$	390		A
			$T_J=125^\circ C$	420		
E_{rec}	Reverse Recovery Energy	$V_{GE}=-15V$	$T_J=25^\circ C$	6.00		mJ
			$T_J=125^\circ C$	7.68		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.074	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.120	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
Weight	Weight of Module	300		g

Package Dimension

Dimensions in Millimeters



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